



RF360
Europe GmbH

Data sheet

SAW duplexer
Automotive telematics
LTE band 7

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Ordering code: B39272B4438P810

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Table of contents

1	Application	4
2	Features	4
3	Package	5
4	Pin configuration	5
5	Matching circuit	6
6	Characteristics	7
7	Maximum ratings	10
8	Transmission coefficients	11
9	Reflection coefficients	14
10	Packing material	15
11	Marking	18
12	Soldering profile	19
13	Annotations	20
14	Cautions and warnings	21
15	Important notes	22

1 Application

- LTE band 7 uplink:
2535 MHz (pass band 70 MHz)
- LTE band 7 downlink:
2655 MHz (pass band 70 MHz)
- Low loss SAW duplexer for band 7 systems
- Low insertion attenuation
- Low amplitude ripple
- Usable pass band 70 MHz
- High isolation between Tx and Rx

2 Features

- Package size $1.8 \pm 0.1 \text{ mm} \times 1.4 \pm 0.1 \text{ mm}$
- Package height 0.45 mm (max.)
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Overmold demonstrated with RF360 specific mold process
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family
(Grade 3: $-40 \text{ }^{\circ}\text{C}$ to $+85 \text{ }^{\circ}\text{C}$)

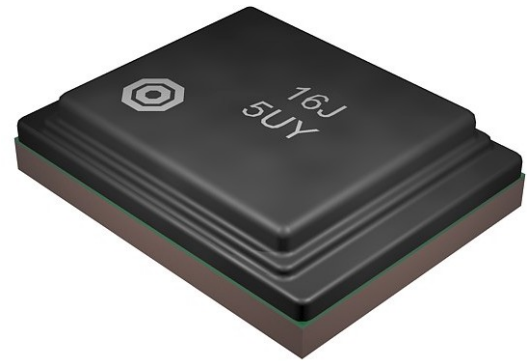
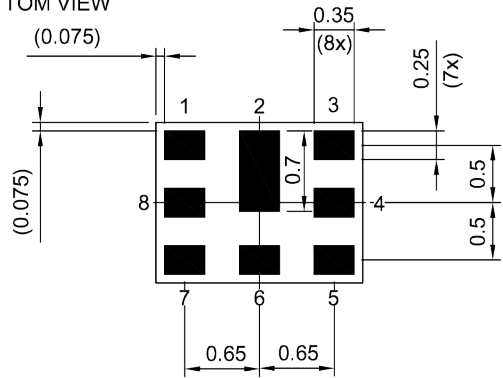


Figure 1: Picture of component with example of product marking.

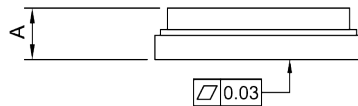
3 Package

BOTTOM VIEW

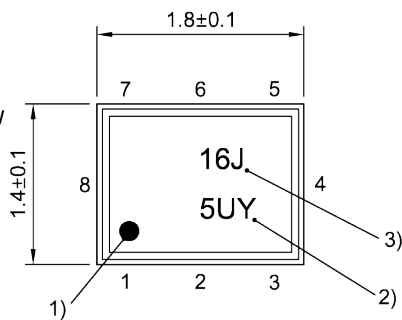


Pad and Pitch Tolerance ± 0.05

SIDE VIEW

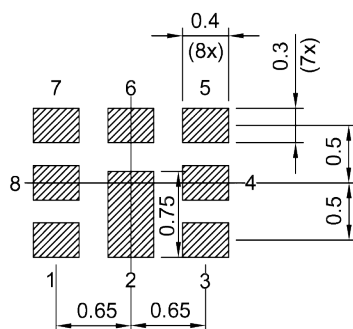


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 21).

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8 Ground

5 Matching circuit

■ $L_{p6} = 3.6 \text{ nH}$

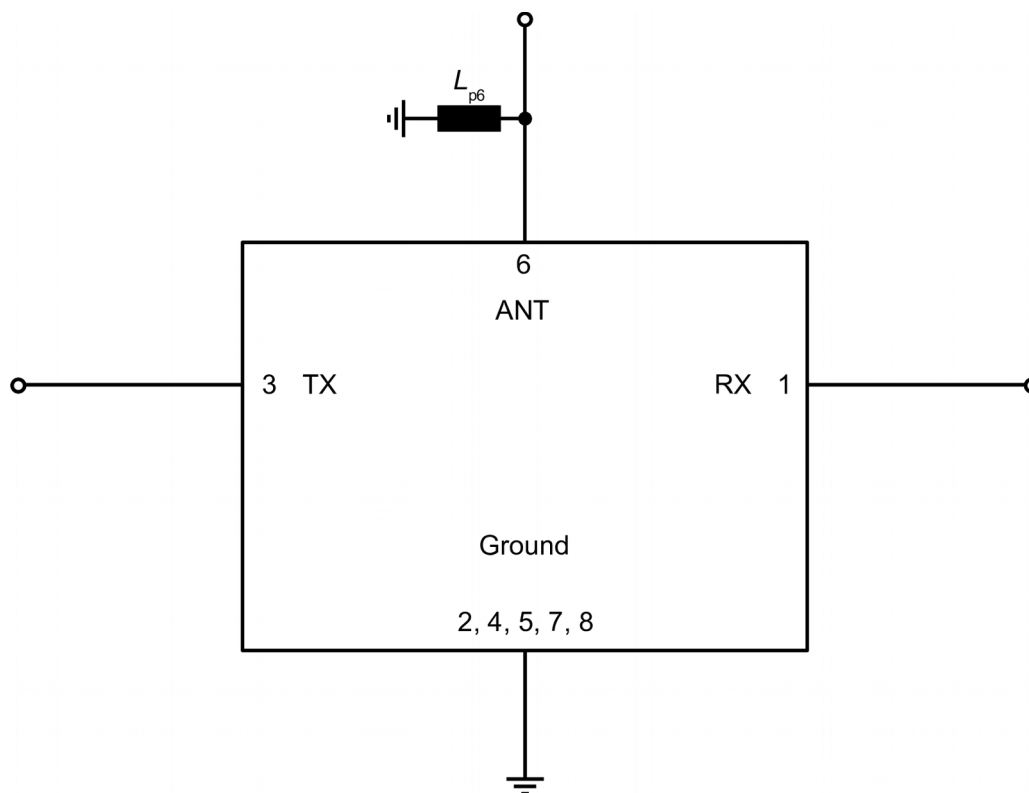


Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_c	—	2535	—	MHz
Maximum insertion attenuation	2500... 2570	MHz	α_{max}	—	1.9	3.2	dB
Amplitude ripple (p-p)	2500... 2570	MHz	$\Delta\alpha$	—	1.1	2.1	dB
Maximum VSWR			VSWR _{max}				
@ TX port	2500... 2570	MHz		—	1.9	2.2	
@ ANT port	2500... 2570	MHz		—	1.8	2.0	
Average attenuation			α_{avg} ²⁾				
Ch12	2457... 2477	MHz		27	48	—	dB
Ch13	2462... 2482	MHz		12	29	—	dB
Minimum attenuation			α_{min}				
	50... 500	MHz		50	57	—	dB
	500... 1710	MHz		33	37	—	dB
	1710... 2400	MHz		30	35	—	dB
	2400... 2472	MHz		38	41	—	dB
	2472... 2481	MHz		6	21	—	dB
	2620... 2690	MHz		46	53	—	dB
	2690... 5300	MHz		35	39	—	dB
	5300... 6000	MHz		40	54	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Average values within each WiFi channel width of 20.0 MHz.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2655	—	MHz
Maximum insertion attenuation			α_{max}				
	2620... 2690	MHz		—	2.3	3.2	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	2620... 2690	MHz		—	1.1	1.9	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	2620... 2690	MHz		—	1.8	2.1	
@ RX port	2620... 2690	MHz		—	2.0	2.3	
Minimum attenuation			α_{min}				
	50... 500	MHz		50	64	—	dB
	500... 1710	MHz		40	45	—	dB
	1710... 2400	MHz		40	44	—	dB
	2400... 2500	MHz		40	50	—	dB
	2500... 2570	MHz		48	52	—	dB
	2715... 2750	MHz		3	20	—	dB
	2750... 6000	MHz		40	46	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 3.6 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Minimum isolation						
		α_{min}				
	1574... 1577	MHz	55	65	—	dB
	2500... 2535	MHz	—	53 ²⁾	—	dB
	2500... 2570	MHz	51	53	—	dB
	2535... 2570	MHz	—	54 ²⁾	—	dB
	2570... 2620	MHz	37	41	—	dB
	2620... 2690	MHz	52	54	—	dB
	5000... 5140	MHz	40	45	—	dB

- ¹⁾ See Sec. Matching circuit (p. 6).
²⁾ Valid for temperature T = +25 °C...+60 °C.

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
Input power @ TX port: 2500 ... 2570 MHz	$P_{IN} = 28\text{ dBm}$	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficients

8.1 TX – ANT

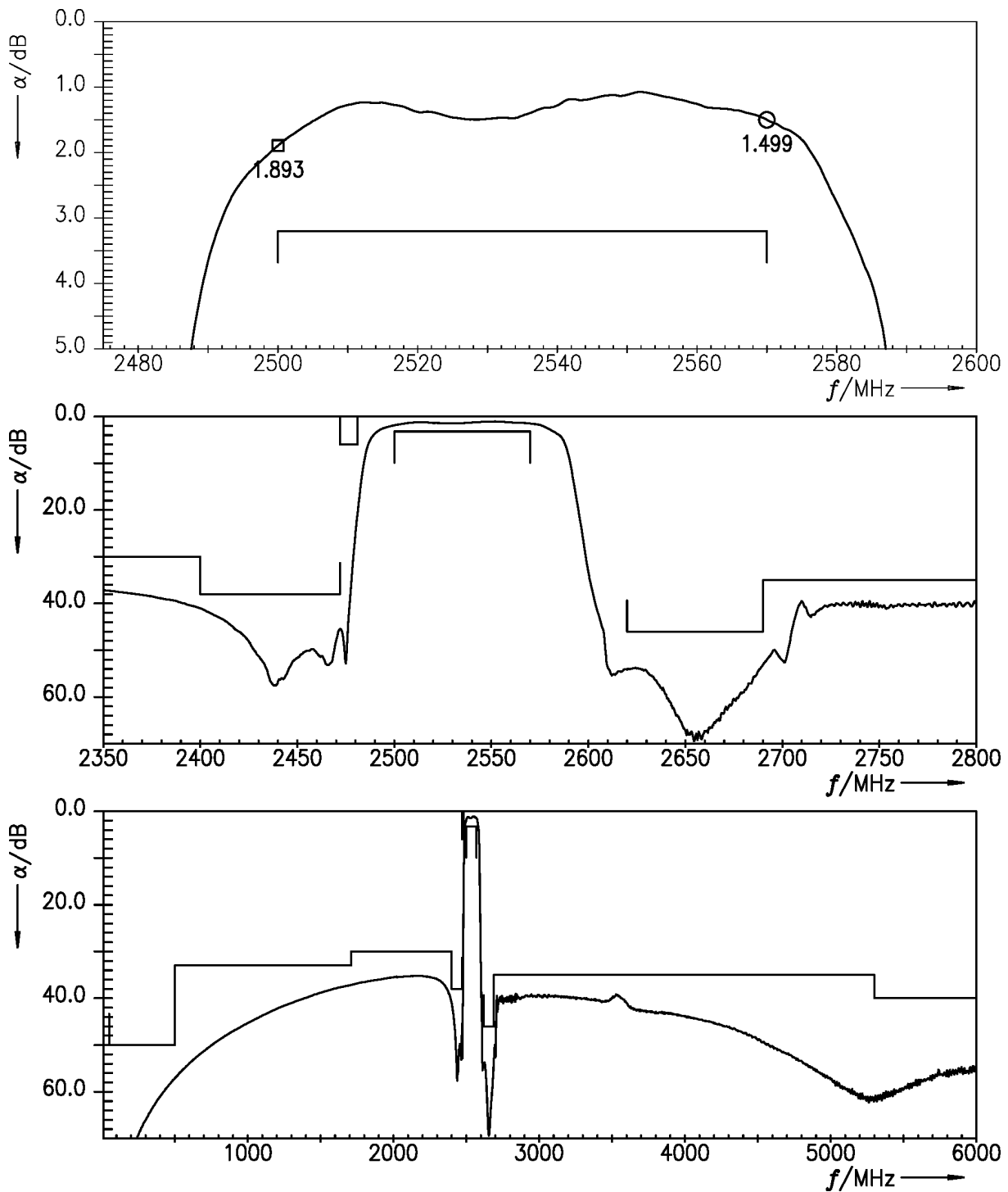


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

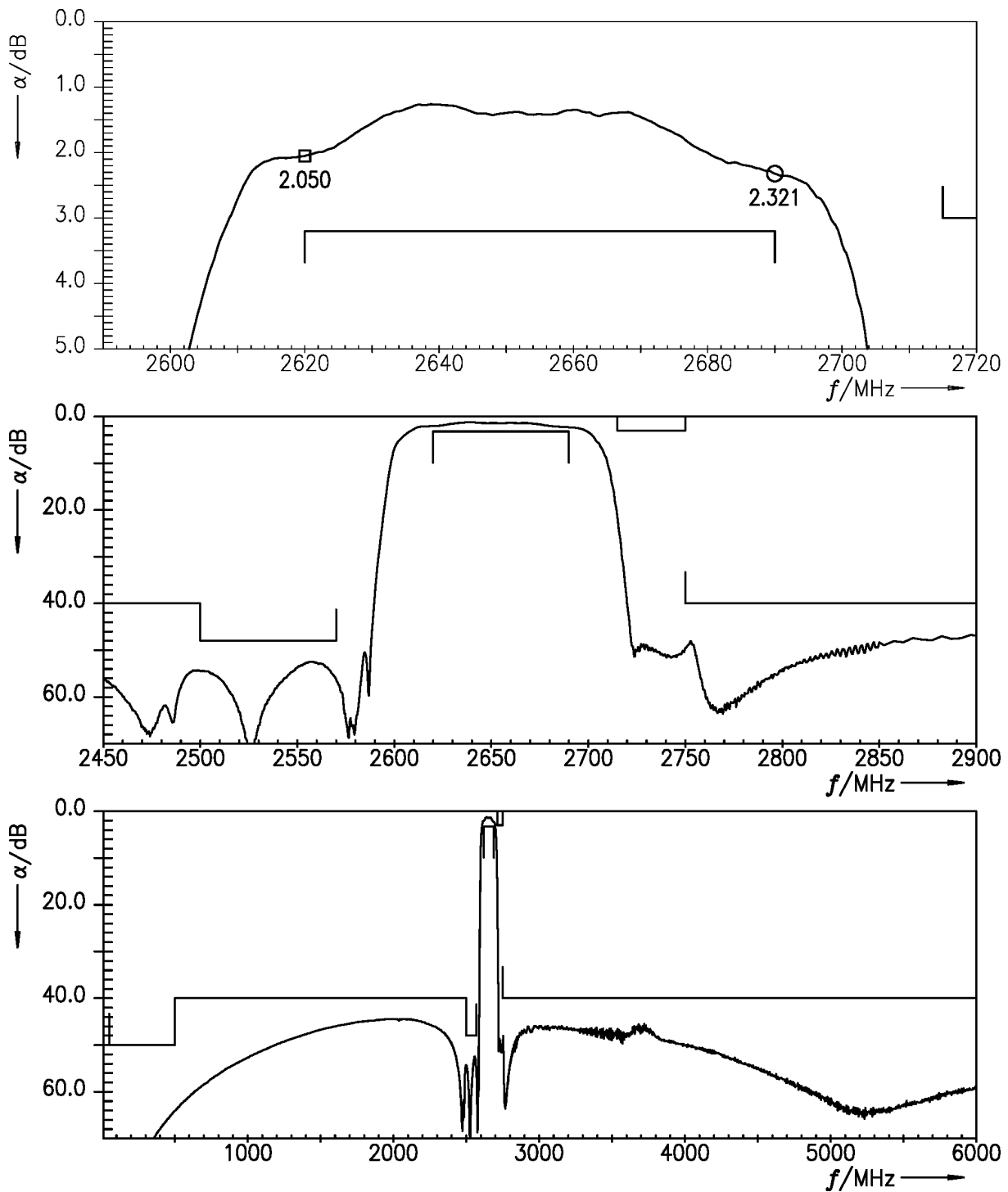


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

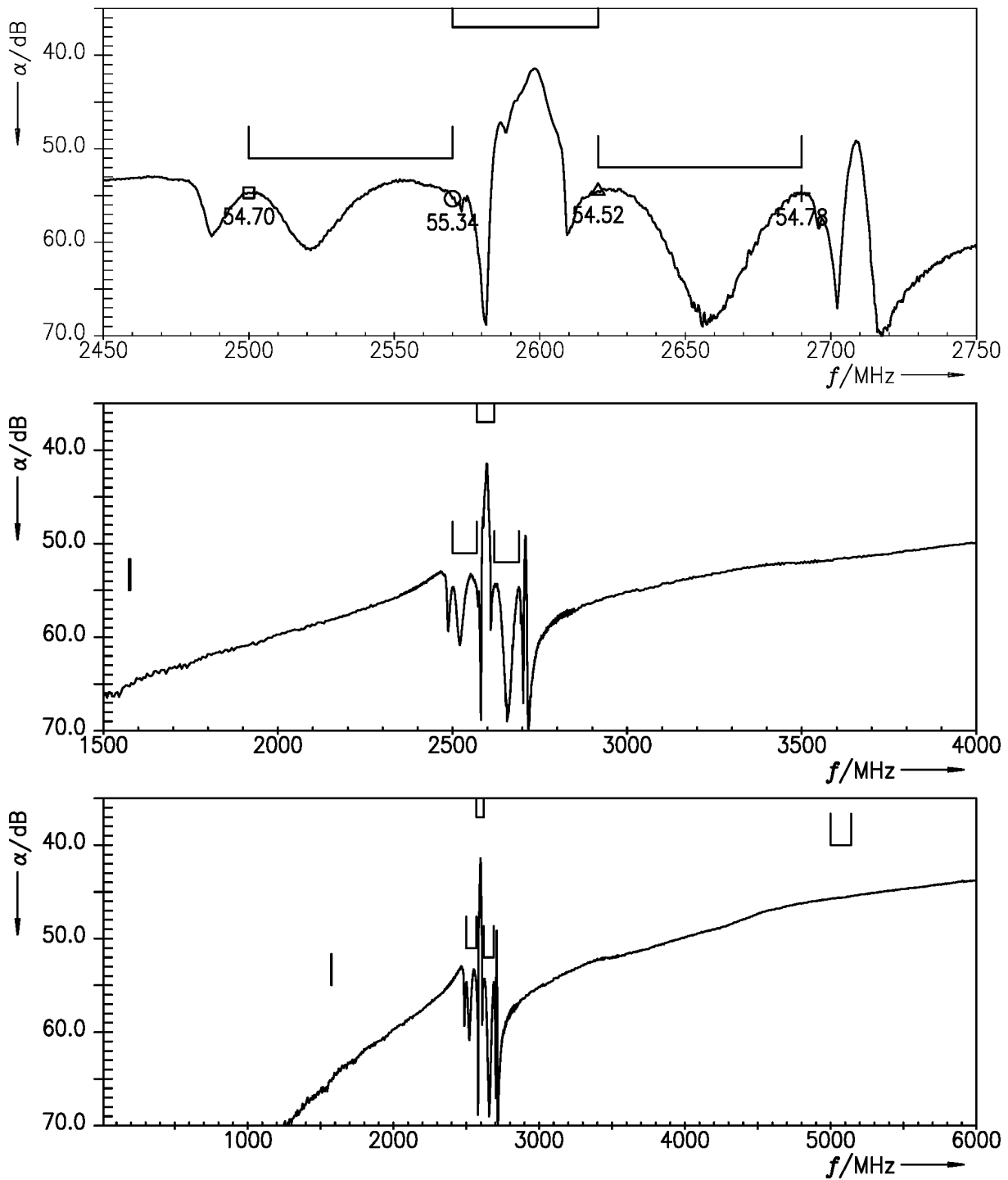


Figure 6: Isolation TX – RX.

9 Reflection coefficients

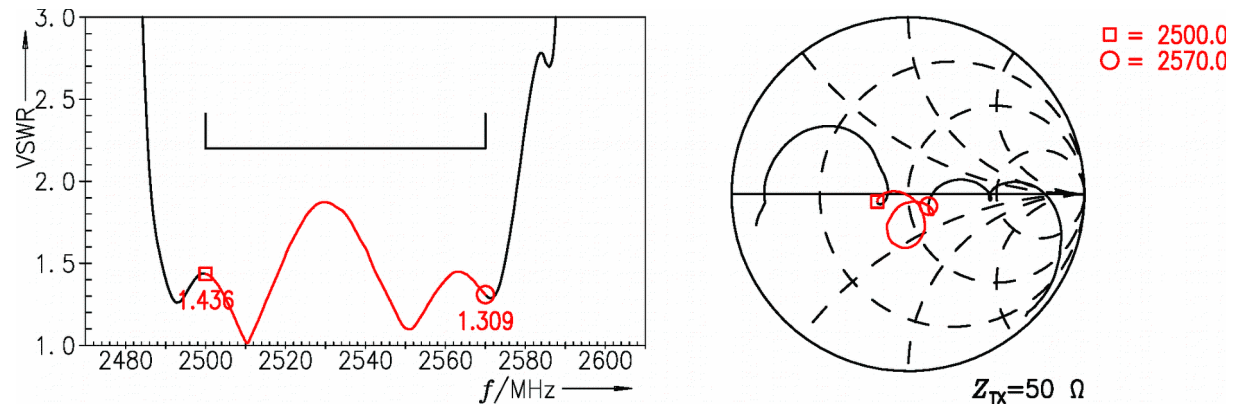


Figure 7: Reflection coefficient at TX port.

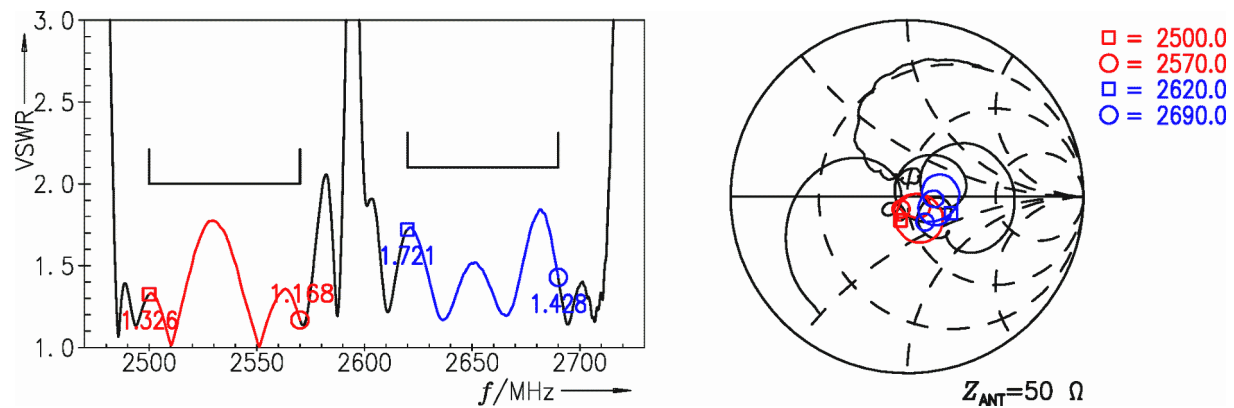


Figure 8: Reflection coefficient at ANT port.

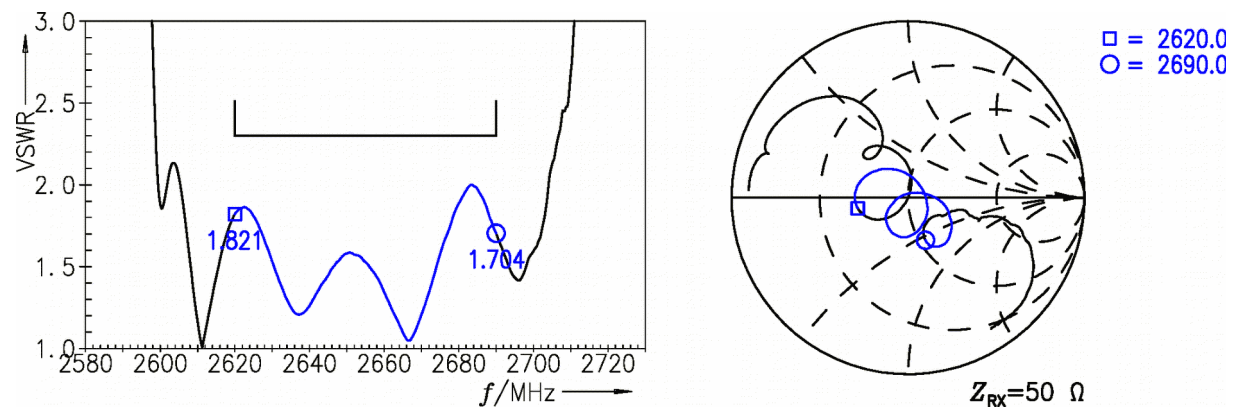


Figure 9: Reflection coefficient at RX port.

10 Packing material

10.1 Tape

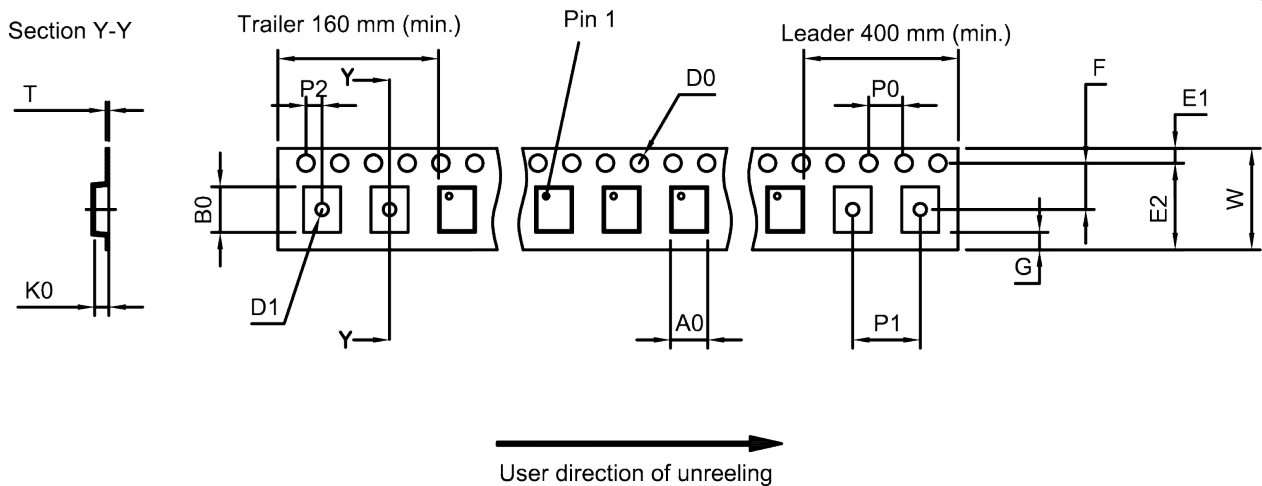


Figure 10: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A_0	1.6 ± 0.05 mm	E_2	6.25 mm (min.)	P_1	4.0 ± 0.1 mm
B_0	2.0 ± 0.05 mm	F	3.5 ± 0.05 mm	P_2	2.0 ± 0.05 mm
D_0	$1.5 + 0.1 / - 0$ mm	G	0.75 mm (min.)	T	0.25 ± 0.03 mm
D_1	$0.8 + 0.1 / - 0$ mm	K_0	0.64 ± 0.05 mm	W	$8.0 + 0.3 / - 0.1$ mm
E_1	1.75 ± 0.1 mm	P_0	4.0 ± 0.1 mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

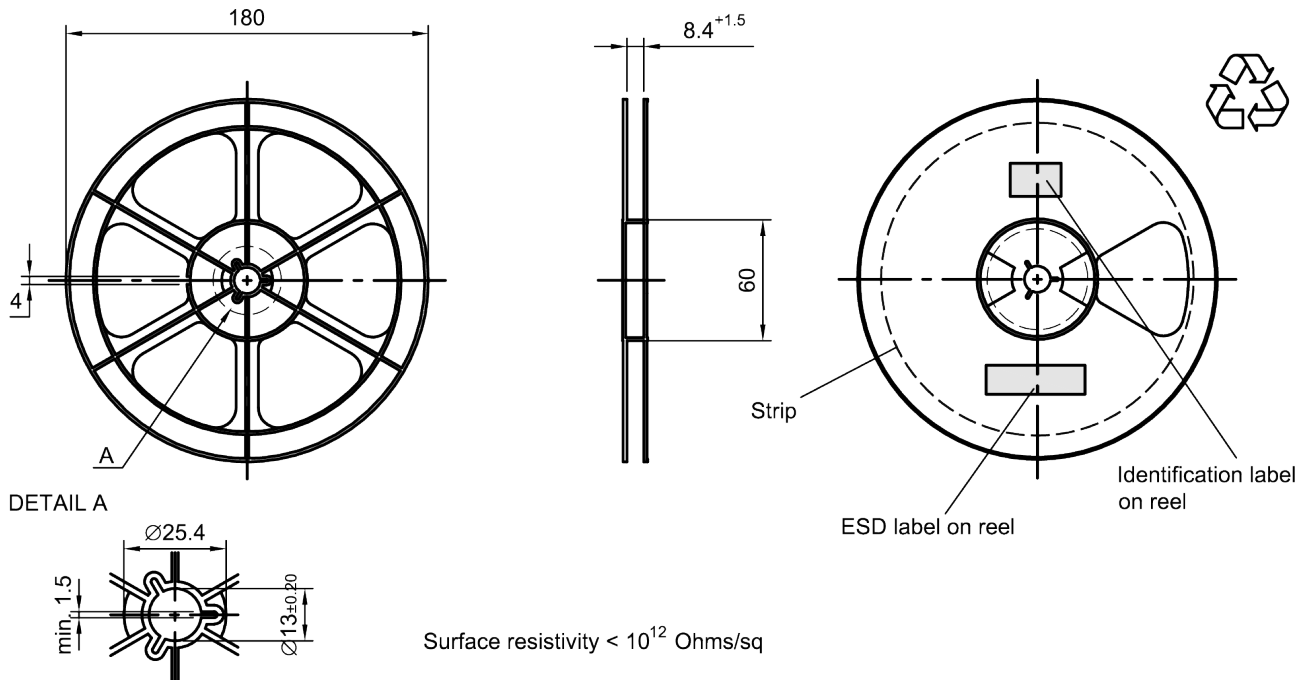


Figure 11: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

Printing
on vacuumbag

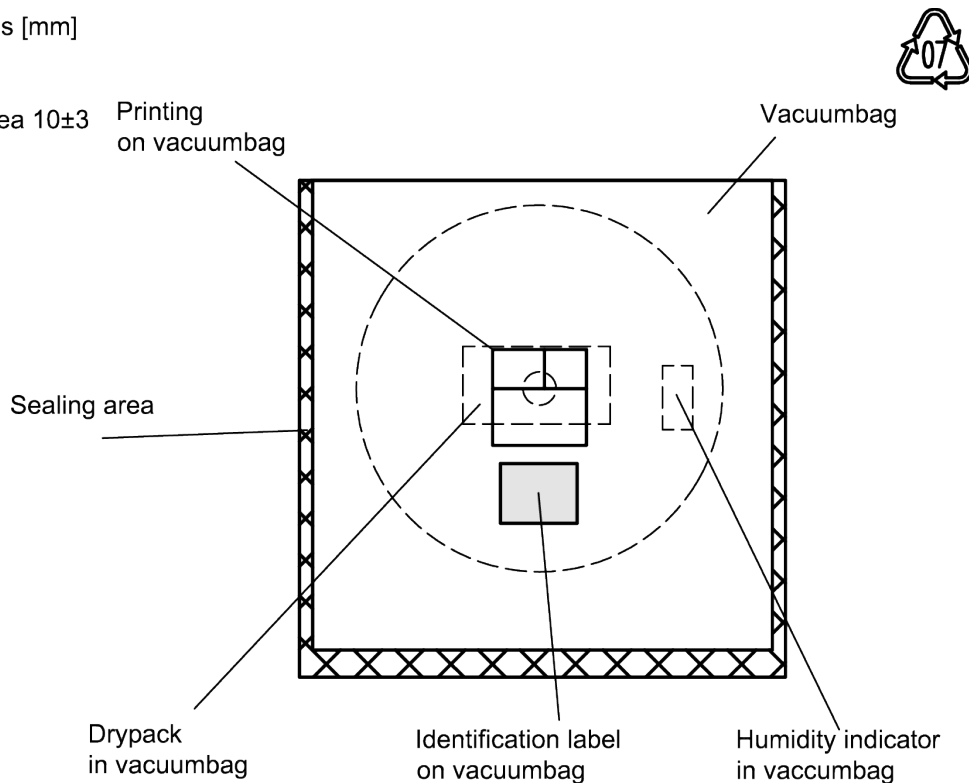


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

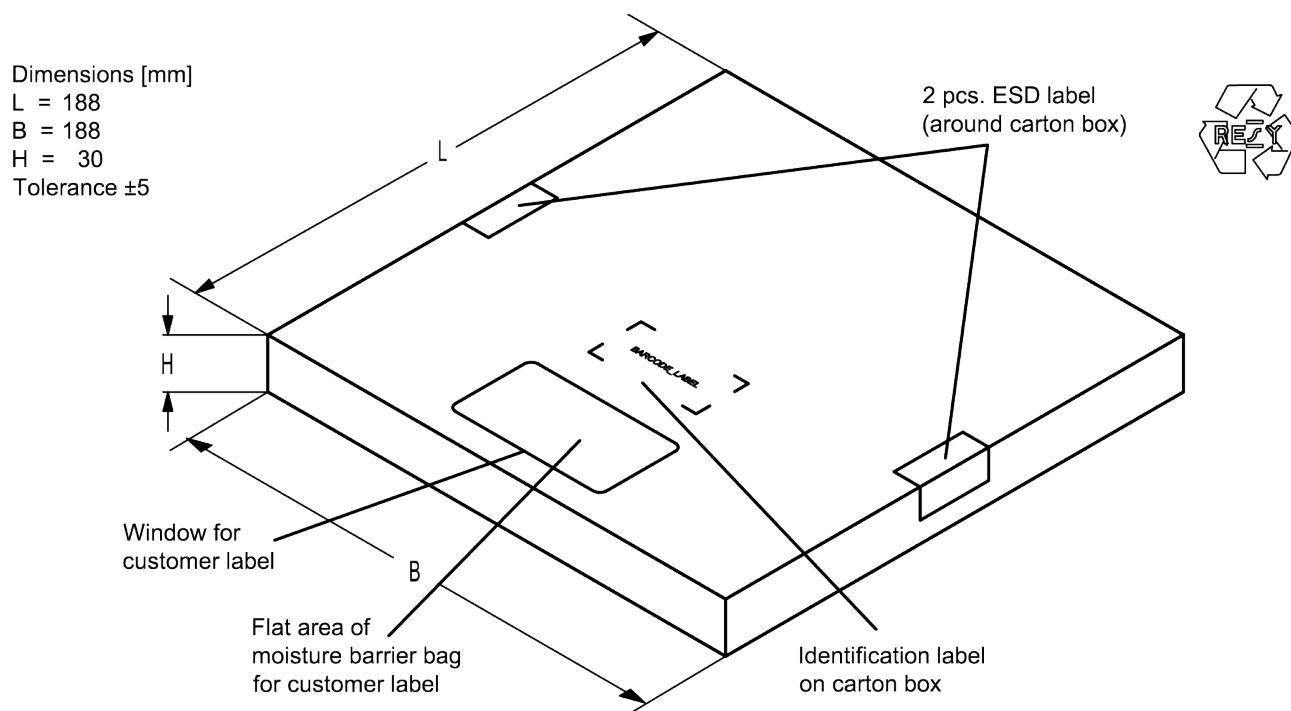


Figure 13: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.
16J \Rightarrow **1234**
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$ **1234**

The BASE32 code for product type B4438 is 4AP.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.
5UY \Rightarrow **12345**
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

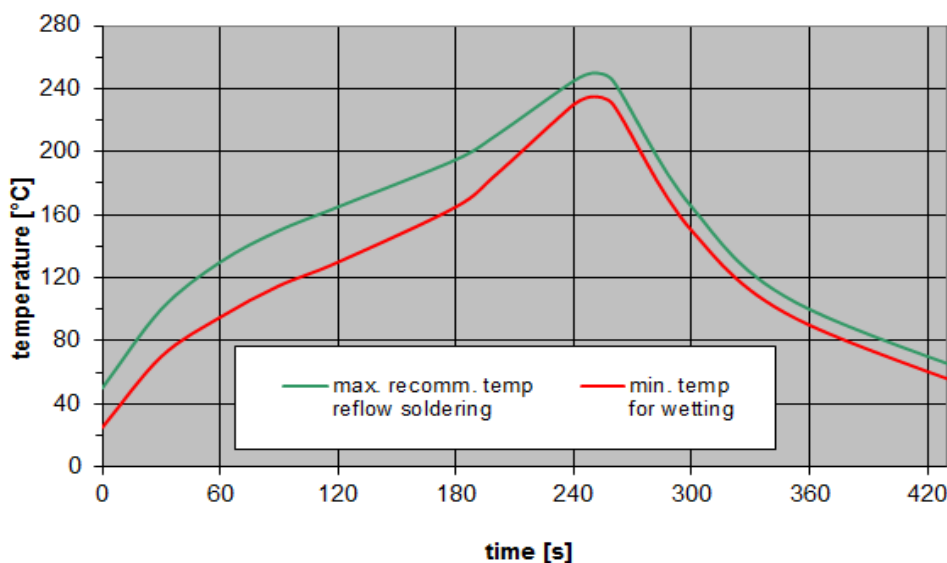


Figure 14: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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